

Advances in Integrated Magnetics for High Frequency Power Conversion Applications



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Introduction

- Increase in DC-DC converter frequencies have enabled passive magnetic components to be fabricated on silicon (< 2 mm² foot print area).
- Windings and Core -losses reduce the efficiency of these devices.

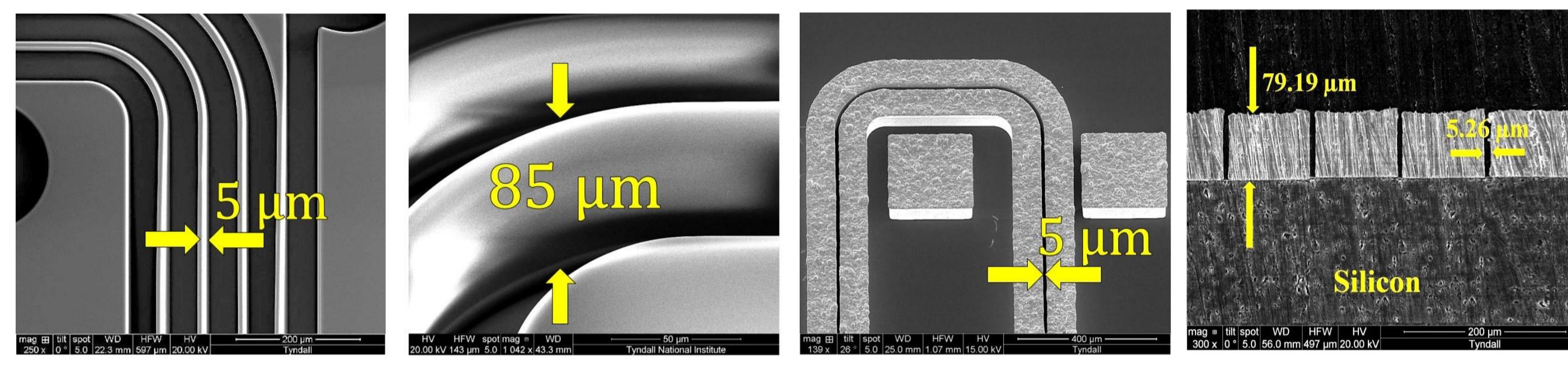
Possible solutions ?

(a) High aspect ratio micro-windings.

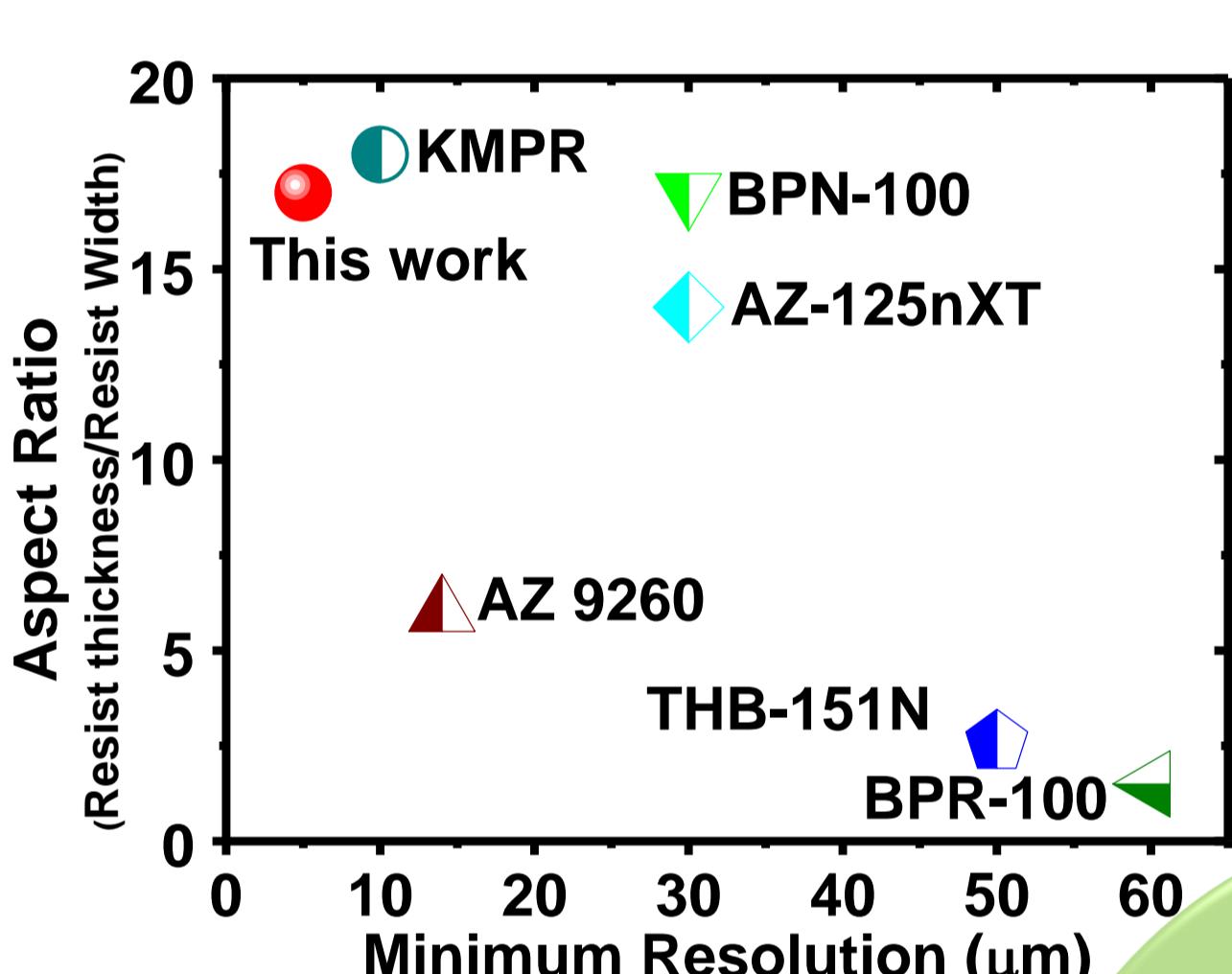
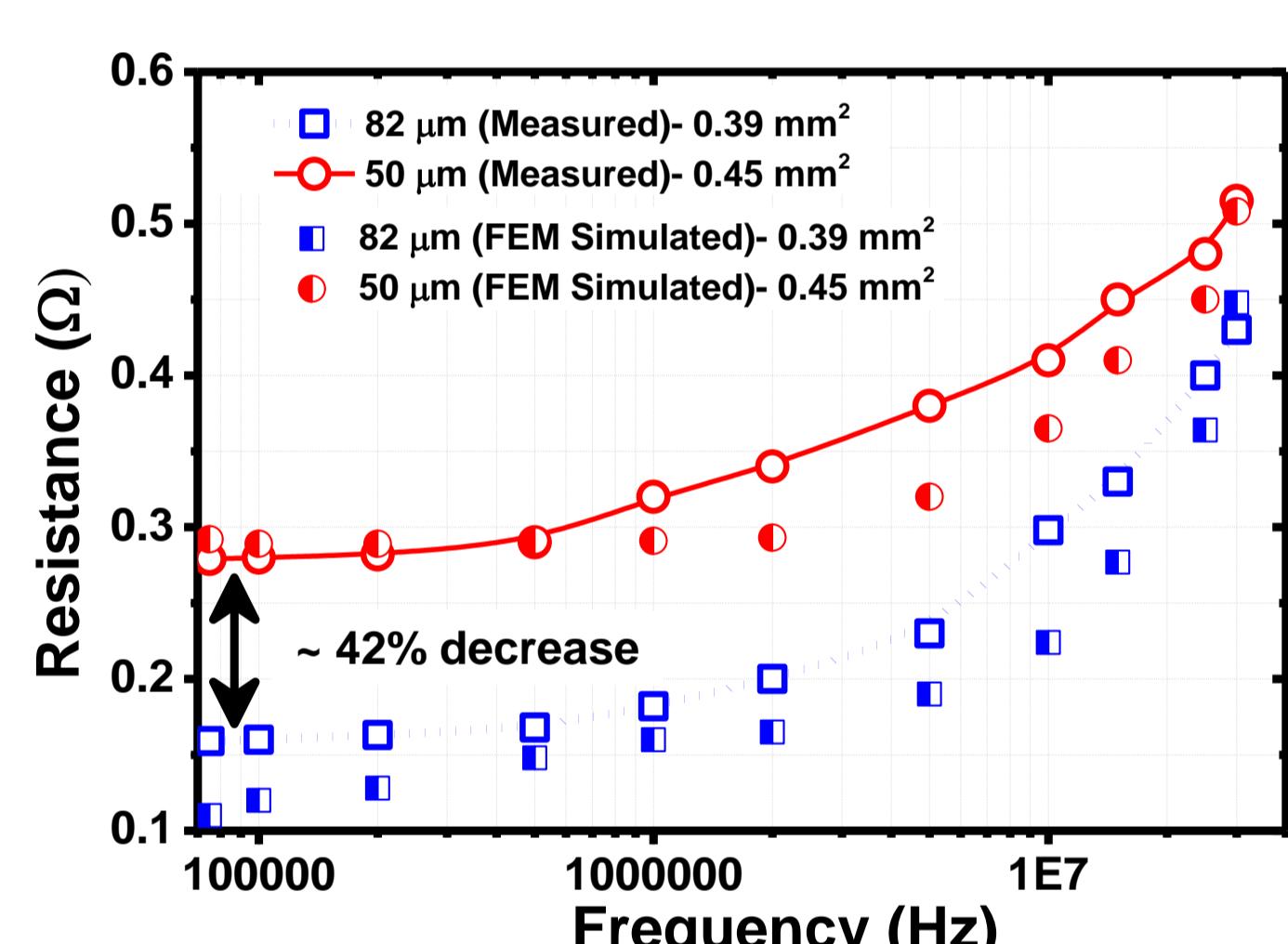
(b) Resistive & Ultra soft magnetic films (c) Magnetic laminations.

I. High-Aspect-Ratio & Resolution Windings

High-aspect-ratio (17:1) and resolution (5 μm) process

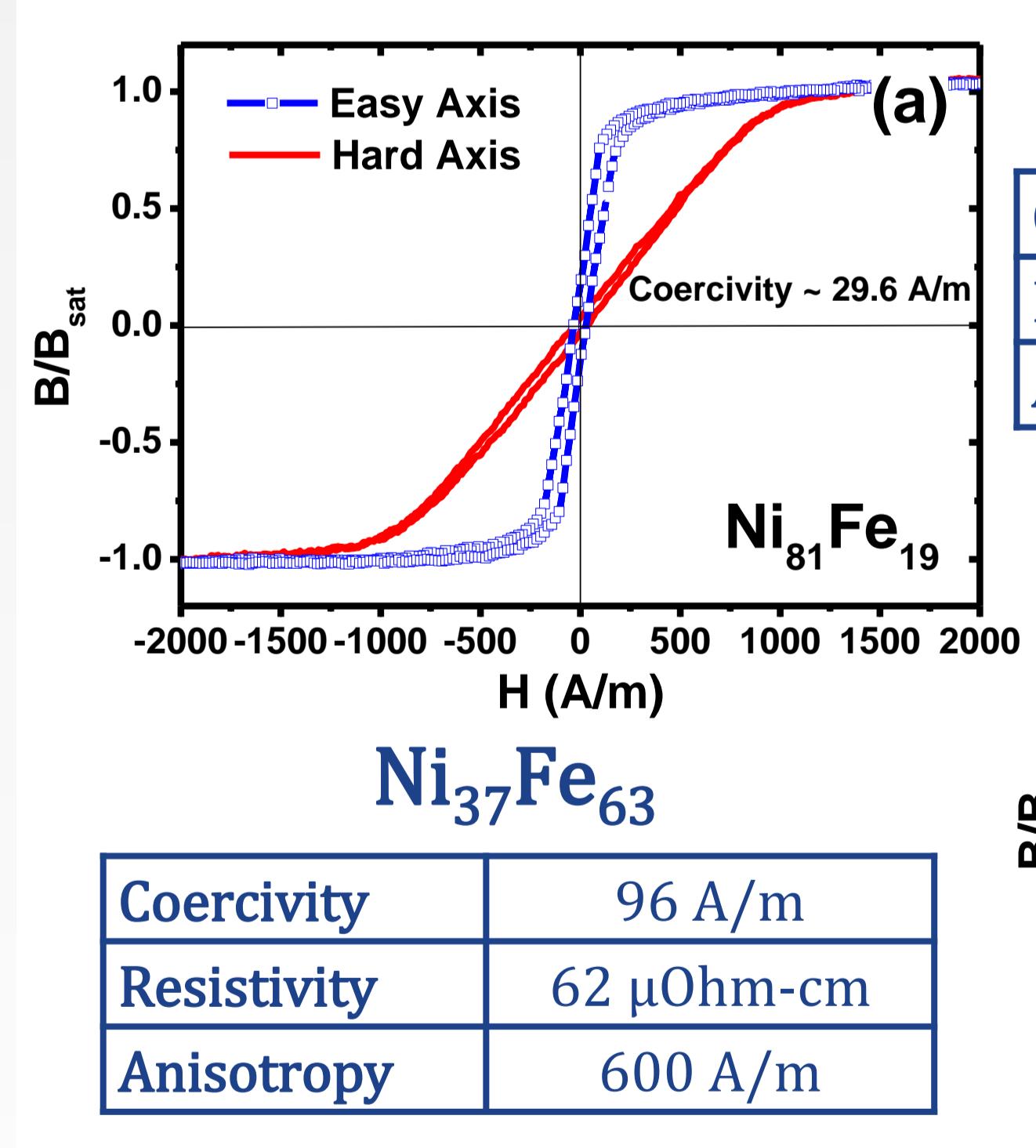


Fabricated windings with 5 μm gap with THB-151N.



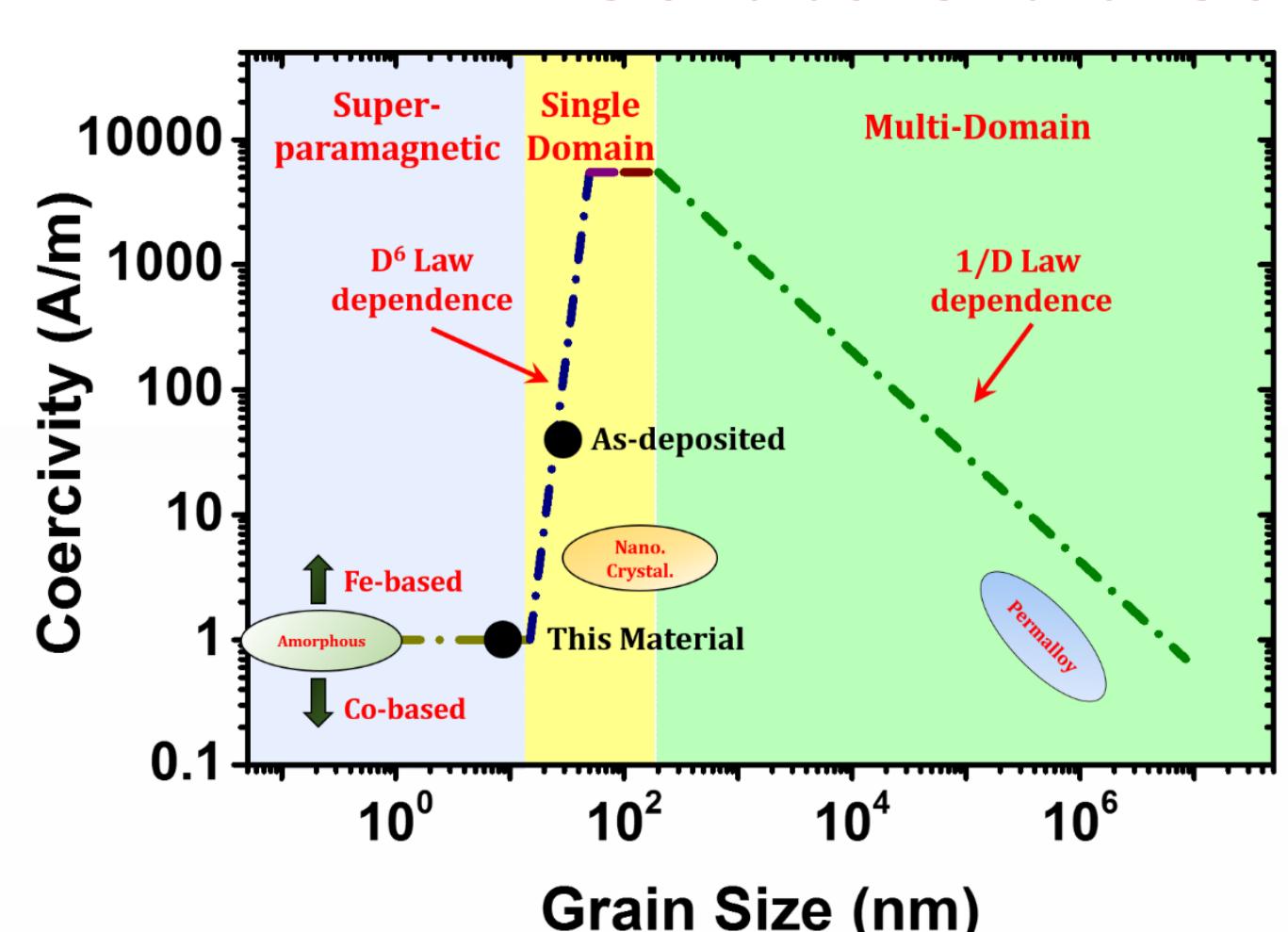
II. Variable and Ultra-soft Magnetics

Electroless DMAB bath to achieve variable Ni-Fe compositions.

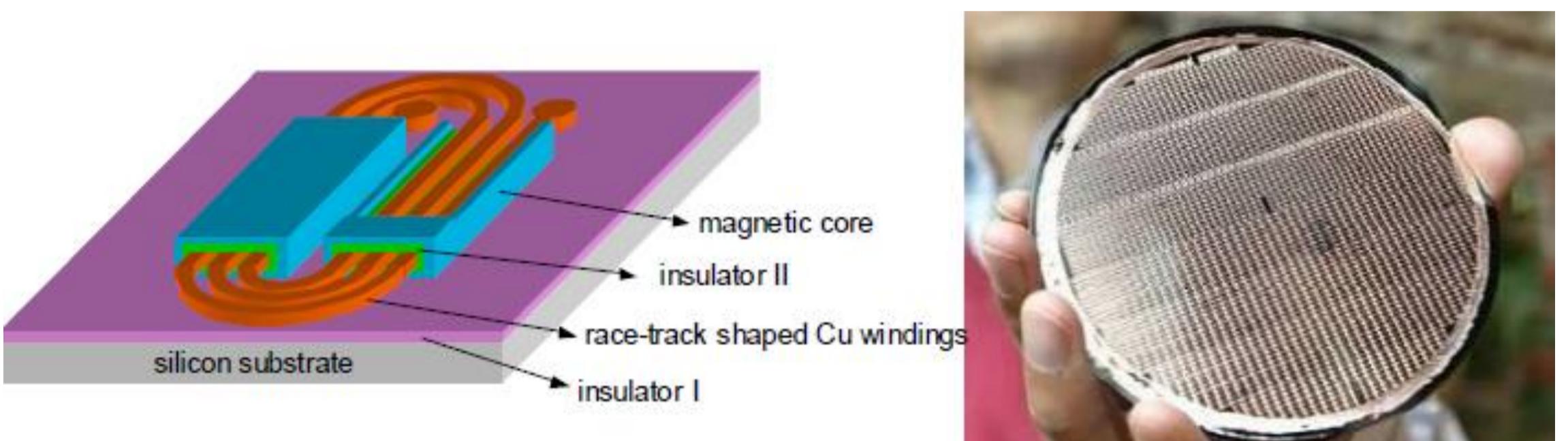
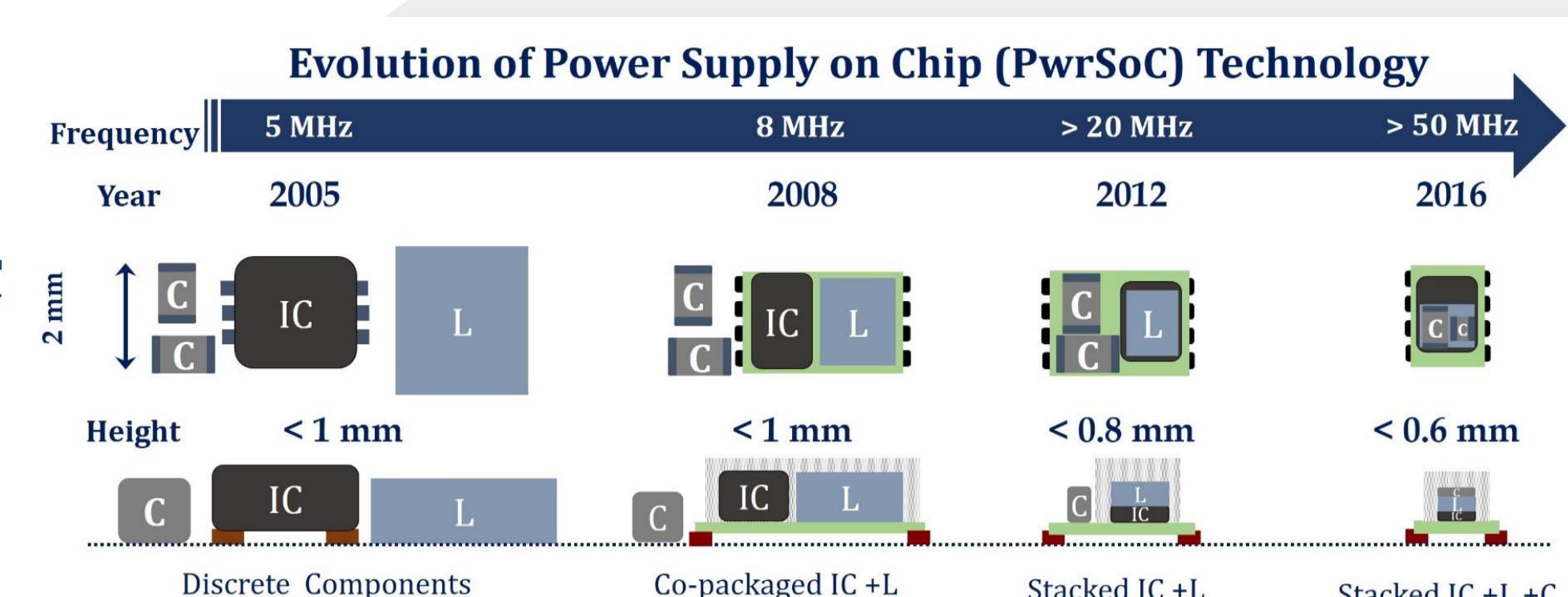


* Ultra-soft material

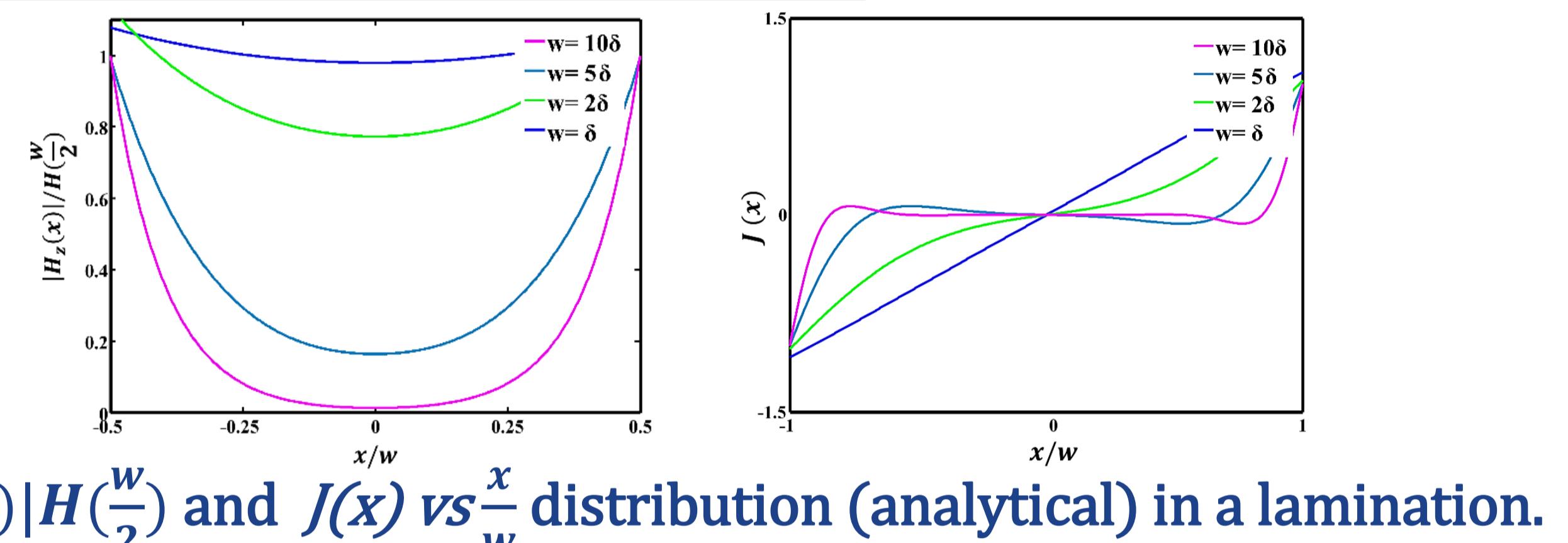
Soft to Ultra-soft Transformation



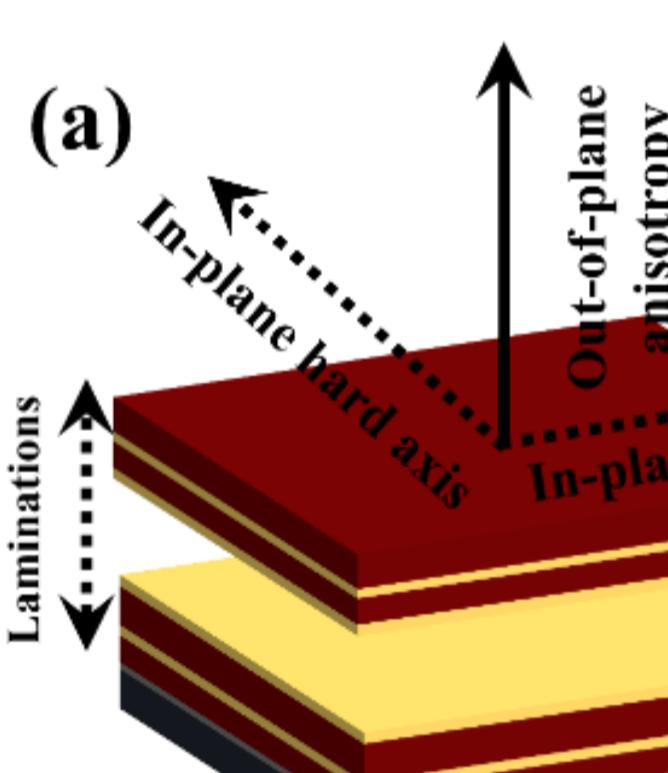
Coercivity	2 A/m
Resistivity	70 μOhm-cm
Anisotropy	900 A/m
Thickness	1 μm - 1.8 μm



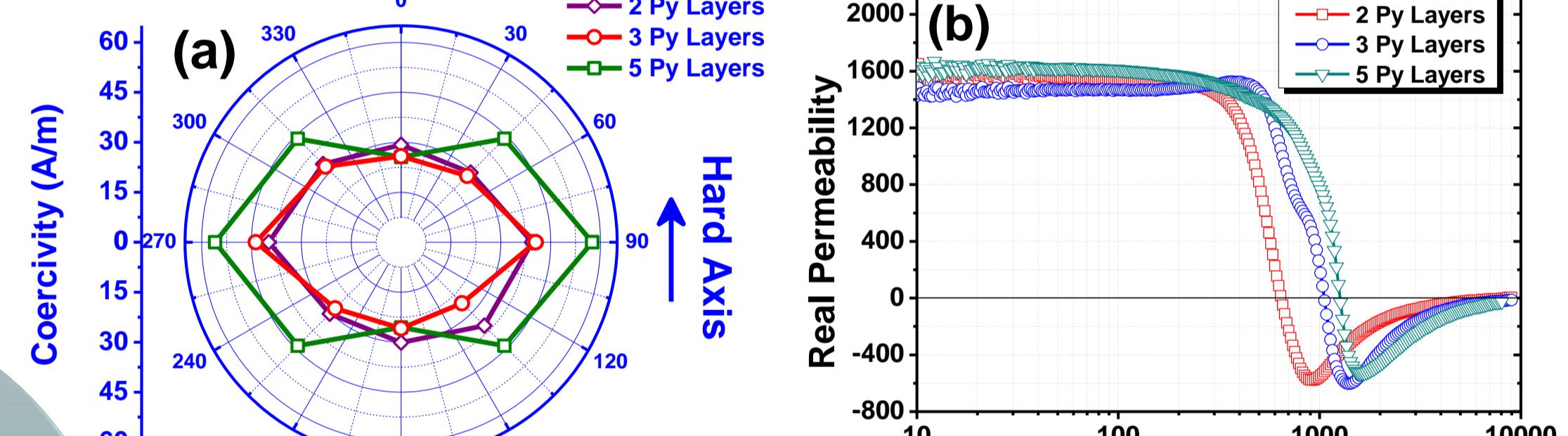
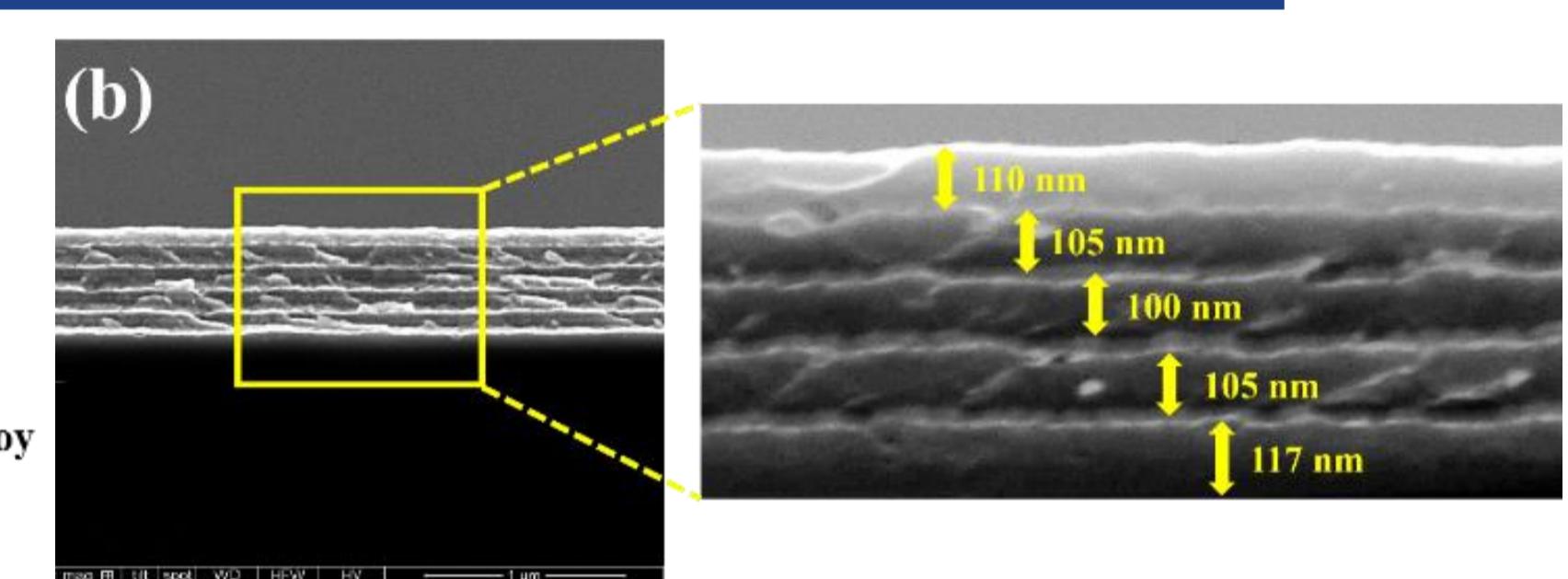
III. Magnetic Laminations



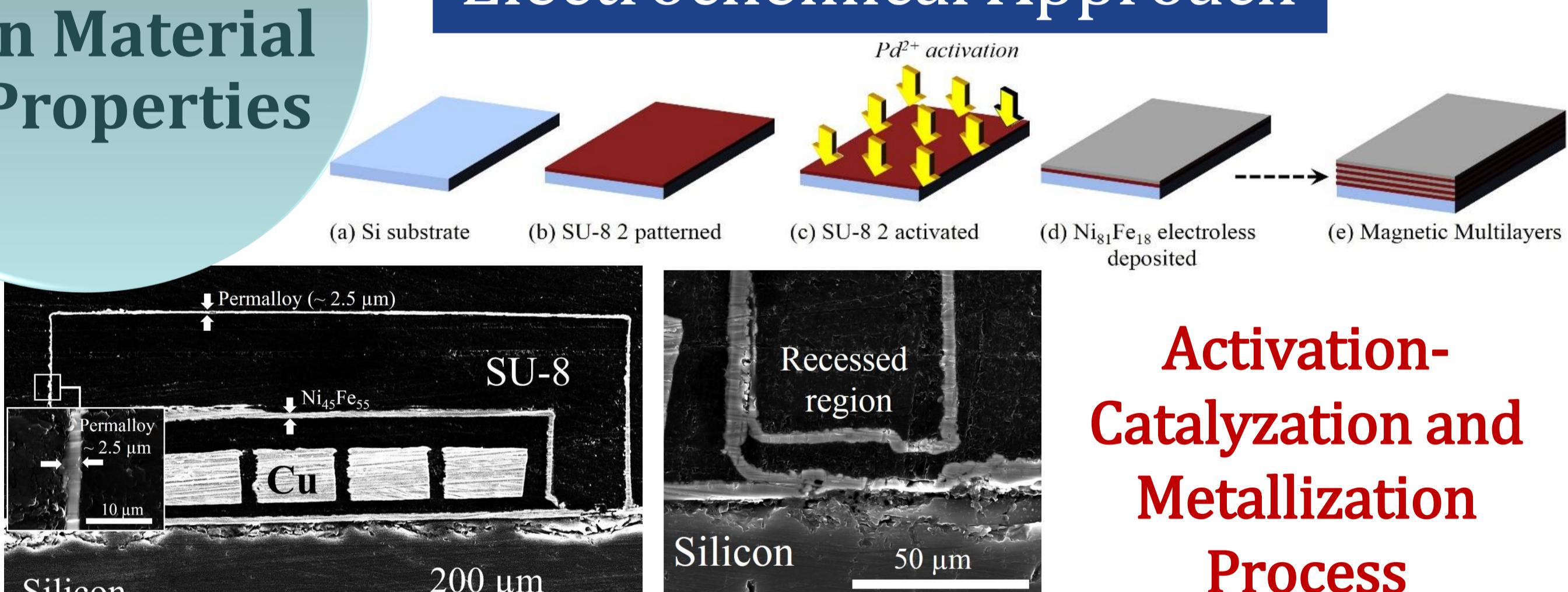
$|H_z(x)|H(\frac{w}{2})$ and $J(x)$ vs $\frac{x}{w}$ distribution (analytical) in a lamination.



Sputter deposition Approach

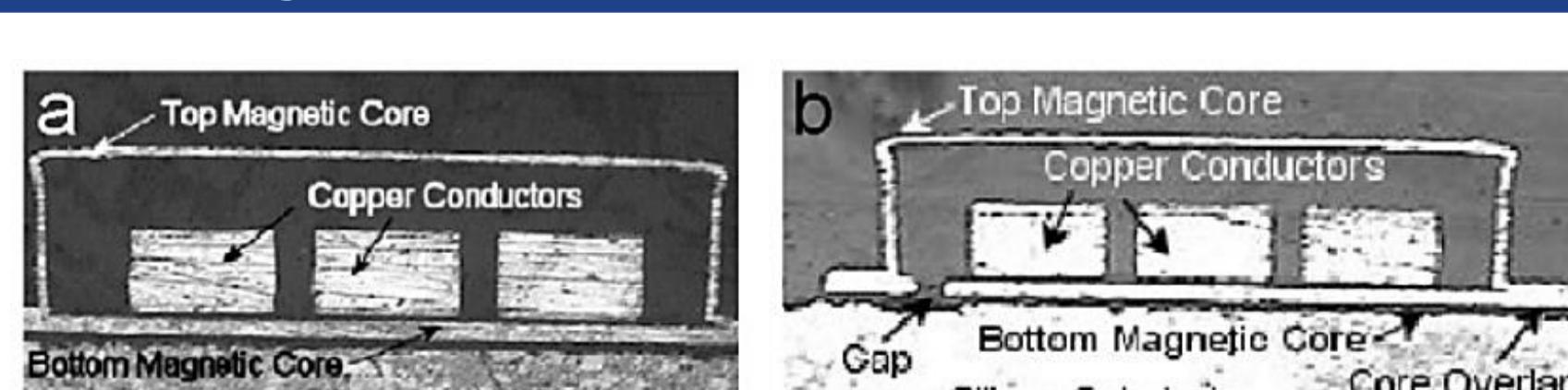


Electrochemical Approach

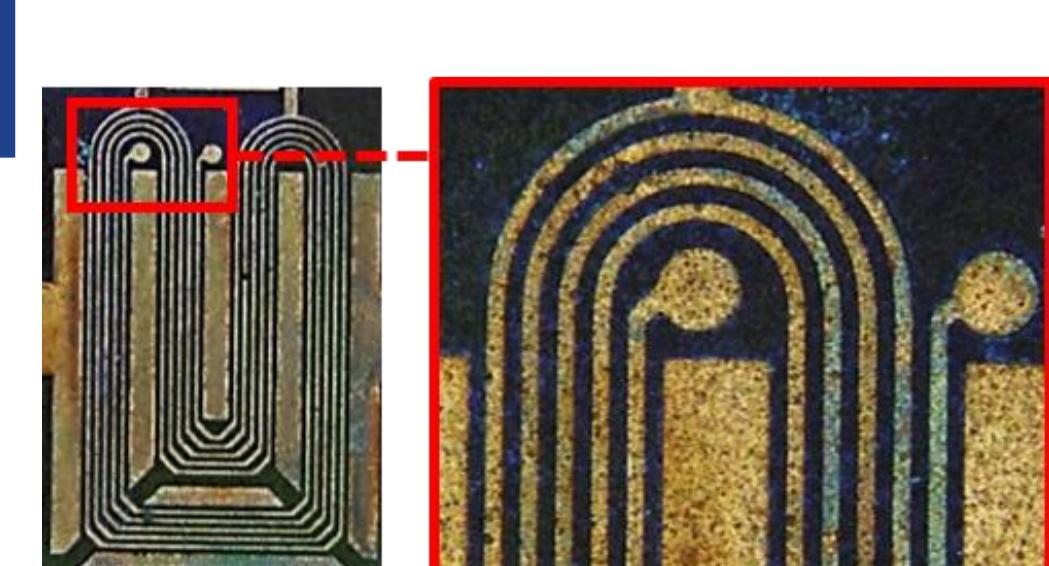


Activation-Catalyzation and Metallization Process

IV. Tyndall Micro-Inductors



Ungapped and Gapped racetrack inductors



Summary

- HAR and density micro-windings.
- Variable and ultra-soft core.
- Nano-laminated cores (electrochemical and sputtered).